

# **LM3537 8-Channel WLED Driver with Four Integrated LDOs**

**Check for Samples: [LM3537](http://www.ti.com/product/lm3537#samples)**

# **<sup>1</sup>FEATURES**

- **• 8-channel Backlight Capability • Overload Protection**
- **Combined Common Features: • Internal ALS Engine; PWM Input to Support CABC • Wide Input Voltage Range: 2.7V to 5.5V**
- **• Built-In Power Supply and Gain Control for • I Ambient Light Sensor • 2 General-Purpose Outputs**
- **• Up to 90% Efficiency**
- **• Adaptive Charge Pump with 1x and 1.5x APPLICATIONS Ggains for Maximum Efficiency • Smartphone Lighting**
- **• 128 Dimming Steps for Group A, Exponential • MP3 Players, Gaming Devices or Linear Dimming Selectable by Register • Digital Cameras Setup**
- **• 8 Linear Dimming States for Group B DESCRIPTION**
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- **• Low Dropout Voltage: 100 mV typ. at 150 mA Load Current**

# **Typical Application Circuit**

- **<sup>2</sup>Lighting: • LDO Input Voltage = 1.8V to VIN\_A**
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	- **<sup>2</sup>C-Compatible Serial Interface**
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LDOs: **LEGOS:** The LM3537 is a highly integrated LED driver **• 4 Programmable LDOs (300 mA/150 mA Output** capable of driving 8 LEDs in parallel for single display **Currents) Currents backlighting applications. Independent LED control** allows for a subset of the main display LEDs to be • **Default Startup Voltage States**<br>• **I** ow Dropout Voltage: 100 mV type at 150 mA<br>• I ow Dropout Voltage: 100 mV type at 150 mA



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# **DESCRIPTION (CONTINUED)**

<sup>2</sup>C-compatible control allows full configurability of the backlighting function. The LM3537 provides multi-zone Ambient Light Sensing allowing autonomous backlight intensity control in the event of changing ambient light conditions. A PWM input is also provided to give the user a means to adjust the backlight intensity dynamically based upon the content of the display.

Four integrated LDOs are fully configurable through I<sup>2</sup>C capable of addressing point-of-load regulation needs for functions such as integrated camera modules. The LDOs can be powered from main battery source, or by a fixed output voltage of an external buck converter (post regulation) leading to higher conversion efficiency.

The LM3537 provides excellent efficiency without the use of an inductor by operating the charge pump in a gain of 3/2 or in Pass Mode. The proper gain for maintaining current regulation is chosen, based on LED forward voltage, so that efficiency is maximized over the input voltage range.

LM3537 is offered in a tiny 30-bump DSBGA package.

# **Connection Diagram**



**Figure 1. 30–Bump DSBGA Package Top View**







**[LM3537](http://www.ti.com/product/lm3537?qgpn=lm3537)**





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.





# **ABSOLUTE MAXIMUM RATINGS(1)(2)(3)**



(1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Operating Ratings are conditions under which operation of the device is specified. Operating Ratings do not imply specified performance limits. For specified performance limits and associated test conditions, see the Electrical Characteristics tables.

All voltages are with respect to the potential at the GND pins.

(3) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

(4) Internal thermal shutdown circuitry protects the device from permanent damage. Thermal shutdown engages at  $T_J = 160^{\circ}C$  (typ.) and disengages at  $T<sub>J</sub> = 155°C$  (typ.).

(5) The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. (MIL-STD-883 3015.7)

# **OPERATING RATINGS(1)(2)**



(1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Operating Ratings are conditions under which operation of the device is specified. Operating Ratings do not imply specified performance limits. For specified performance limits and associated test conditions, see the Electrical Characteristics tables.

All voltages are with respect to the potential at the GND pins.

(3) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature (T<sub>A-MAX</sub>) is dependent on the maximum operating junction temperature (T<sub>J-MAX-OP</sub> = 110°C), the maximum power dissipation of the device in the application (P<sub>D-MAX</sub>), and the junction-to ambient thermal resistance of the part/package in the application ( $\theta_{JA}$ ), as given by the following equation:  $T_{A-MAX} = T_{J-MAX\ OP} - (\theta_{JA} \times P_{D-MAX})$ .

# **THERMAL PROPERTIES(1)**



(1) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

Junction-to-ambient thermal resistance is highly dependent on application and board layout. In applications where high maximum power dissipation exists, special care must be paid to thermal dissipation issues in board design. For more information, please refer to Texas Instruments' Application Note AN-1112: DSBGA Wafer Level Chip Scale Package (Literature Number [SNVA009\)](http://www.ti.com/lit/pdf/SNVA009).



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# <span id="page-4-0"></span>**CHARGE PUMP AND LED DRIVERS ELECTRICAL CHARACTERISTICS(1)(2)**

Limits in standard typeface are for  $T_J = 25^\circ \text{C}$ , and limits in **boldface** type apply over the operating ambient temperature range (−30°C to +85°C). Unless otherwise specified: V<sub>IN\_A</sub> = 3.6V; V<sub>HWEN</sub> = V<sub>IN\_A</sub>; V<sub>Dx</sub> = 0.4V; GroupA = GroupB = Fullscale Current;  $C_1 = C_2 = C_{INA} = C_{OUT} = 1.0 \mu F^{(3)}$ 



(1) All voltages are with respect to the potential at the GND pins.

 $(2)$  Min and Max limits are specified by design, test, or statistical analysis. Typical numbers are not ensured, but do represent the most likely norm.

(3)  $C_{IN\_X}$ ,  $C_{OUT}$ ,  $C_{LDOX}$ ,  $C_{SEN}$ ,  $C_1$ , and  $C_2$ : Low-ESR Surface-Mount Ceramic Capacitors (MLCCs) used in setting electrical characteristics.<br>(4) The total output current can be split between the two groups (IDx =

(4) The total output current can be split between the two groups (IDx = 25 mA Max). Under maximum output current conditions, special attention must be given to input voltage and LED forward voltage to ensure proper current regulation. The maximum total output current for the LM3537 should be limited to 180 mA.

(5) For the two groups of current sinks on a part (group A and group B), the following are determined: the maximum sink current in the group (MAX), the minimum sink current in the group (MIN), and the average sink current of the group (AVG). For each group, two matching numbers are calculated: (MAX-AVG)/AVG and (AVG-MIN)/AVG. The largest number of the two (worst case) is considered the matching figure for the group. The matching figure for a given part is considered to be the highest matching figure of the two groups. The typical specification provided is the most likely norm of the matching figure for all parts.

(6) For each Dxpin, headroom voltage is the voltage across the internal current sink connected to that pin. For group A and B current sinks,  $V_{HRx} = V_{OUT} - V_{LED}$ . If headroom voltage requirement is not met, LED current regulation will be compromised.

Specified by design.

(8) Turn-on time is measured from the moment the charge pump is activated until the  $V_{\text{OUT}}$  crosses 90% of its target value.

# **LOGIC INTERFACE CHARACTERISTICS(1)(2)**



(1) All voltages are with respect to the potential at the GND pins.

 $(2)$  Min and Max limits are specified by design, test, or statistical analysis. Typical numbers are not ensured, but do represent the most likely norm.

(3) SCL and SDA should be glitch-free in order for proper device control to be realized. See [Figure](#page-7-0) 2 for timing specification details.

 $(4)$  SCL is tested with a 50% duty-cycle clock.

(5)  $V_{\text{OUT\_S}}$  = SBIAS pin output voltage. The voltage level of the GPOs depends on the sbias\_en-bit: '1'; GPOs will behave as push-pull outputs and will reference the high-side to the voltage of SBIAS. '0'; GPOs will ac configuration, they can be high-side referenced to any voltage equal to, or less than, the VIN\_A of the LM3537. Output High Level (V<sub>OH</sub>) specification is valid only for push-pull -type outputs.



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# **VOLTAGE REGULATORS ELECTRICAL CHARACTERISTICS(1)(2)**

Unless otherwise noted, V<sub>IN\_A</sub>= V<sub>IN\_B</sub> = V<sub>IN\_C</sub> = 3.6V, C<sub>IN\_A</sub> = 1 µF, C<sub>IN\_B</sub> = 100 nF, C<sub>IN\_C</sub> = 2.2 µF, C<sub>LDOX</sub>= 1 µF, HWEN = high. Limits in standard typeface are for T<sub>J</sub> = 25°C, and limits in **boldface** type apply over the operating ambient temperature range  $(-30^{\circ}$ C to  $+85^{\circ}$ C).<sup>(3)</sup>



(1) All voltages are with respect to the potential at the GND pins.

 $(2)$  Min and Max limits are specified by design, test, or statistical analysis. Typical numbers are not ensured, but do represent the most likely norm.

(3) C<sub>IN\_C</sub>, C<sub>LDOX</sub> : Low-ESR Surface-Mount Ceramic Capacitors (MLCCs) used in setting electrical characteristics.

(4) Time needed for  $V_{\text{OUTLDO}}$  to reach 95% of final value.

# **SENSOR INTERFACE ELECTRICAL CHARACTERISTICS**

Unless otherwise noted, V<sub>IN\_A</sub> = 3.6V, C<sub>IN\_A</sub> = 1 µF, C<sub>IN\_B</sub> = 100 nF, C<sub>IN\_C</sub> = 2.2 µF, C<sub>SEN</sub>= 1 µF, HWEN = high. Limits in standard typeface are for T<sub>J</sub> = 25°C, and limits in **boldface** type apply over the operating ambient temperature range (−30°C to  $+85^{\circ}$ C).



(1) In addition to Quiescent Supply Current (IQ) drawn by the charge pump. (See Charge Pump and LED Drivers Electrical [Characteristics.](#page-4-0))

<span id="page-7-0"></span>(2) Specified by design.



**Figure 2. Timing Parameters**



**[LM3537](http://www.ti.com/product/lm3537?qgpn=lm3537)**



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# **TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

Unless otherwise specified:  $V_{IN\_A,B,C} = 3.6V$ ,  $C_{IN\_A} = C_{OUT} = 1.0 \mu F$ ,  $C_{IN\_B} = 0.1 \mu F$ ,  $C_{IN\_C} = 4.7 \mu F$ ,  $C_1 = C_2 = 1.0 \mu F$ ,  $C_{LDOx} = 1.0 \mu F$  $\mu$ F, T<sub>A</sub> = 25°C.



(1) For the two groups of current sinks on a part (group A and group B), the following are determined: the maximum sink current in the group (MAX), the minimum sink current in the group (MIN), and the average sink current of the group (AVG). For each group, two matching numbers are calculated: (MAX-AVG)/AVG and (AVG-MIN)/AVG. The largest number of the two (worst case) is considered the matching figure for the group. The matching figure for a given part is considered to be the highest matching figure of the two groups. The typical specification provided is the most likely norm of the matching figure for all parts.









# **Circuit Description**

# **OVERVIEW**

The LM3537 is a white LED driver system based upon an adaptive  $3/2x - 1x$  CMOS charge pump capable of supplying up to 180 mA of total output current. With two separately controlled groups of constant current sinks, the LM3537 is an ideal solution for platforms requiring a single white LED driver for main display and sub display (or keypad). The tightly matched current sinks ensure uniform brightness from the LEDs across the entire smallformat display.

Each LED is configured in a common anode configuration, with the peak drive current set to 25 mA. An I<sup>2</sup>Ccompatible interface is used to enable the device and vary the brightness within the individual current sink groups. For group A, 128 brightness control levels are available (user defined linear or exponential dimming curve). Group B has 8 linearly-spaced analog brightness levels.

The LM3537 provides an input for an Ambient Light Sensor to adaptively adjust the diode current based on ambient conditions, and a PWM pin to allow the diode current to be pulse width modulated to work with a display driver utilizing dynamic or content adjusted backlight control (DBC or CABC). Additionally, the device provides 20 mA power supply output for the sensor. The GPOs can also be configured to serve as a gain control interface for sensors with HW-controlled gain.

The LM3537 also integrates three 150-mA LDO and one 300-mA LDO voltage regulators, which can be turned on/off using separate enable bits on each LDO. Each LDO operates with a power rail input voltage range between 1.8 V and 5.5V allowing them to be supplied from the battery or a step-down converter. Furthermore, the regulated output voltages can be adjusted through the serial bus.

## **CIRCUIT COMPONENTS**

## **Charge Pump**

The input to the  $3/2x - 1x$  charge pump is connected to the  $V_{IN\_A}$  pin, and the regulated output of the charge pump is connected to the  $V_{\text{OUT}}$  pin. The operating input voltage range of the LM3537 is 2.7V to 5.5V. The device's regulated charge pump has both open-loop and closed-loop modes of operation. When the device is in open loop, the voltage at  $V_{OUT}$  is equal to the gain times the voltage at the input. When the device is in closed loop, the voltage at  $V_{OUT}$  is regulated to 4.2V (typ.). The charge pump gain transitions are actively selected to maintain regulation based on LED forward voltage and load requirements.

## **Diode Current Sinks**

The matched current outputs are generated with a precision current mirror that is biased off the charge pump output. Matched currents are ensured with the use of tightly matched internal devices and internal mismatch cancellation circuitry. There are eight regulated current sinks configurable into 2 different lighting regions.

## **Ambient Light Sensing (ALS) and Interrupt**

The LM3537 provides an Ambient Light Sensing input for use with ambient backlight control. Connecting the anode of a photo diode to this pin and configuring the appropriate ALS resistor, the LM3537 can be configured to adjust the LED current to five unique settings corresponding to four adjustable light region trip points. Additionally, when the LM3537 determines that an ambient condition has changed, the interrupt pin, when connected to a pullup resistor will toggle to a '0' alerting the controller. Available resistor values are shown in [Table](#page-13-0) 1 below.

<span id="page-13-0"></span>

# **Table 1. ALS Resistor Values**

## **Automatic Gain Change**

GPO pins of the LM3537 can be configured to serve as a gain control interface for sensors with HW controlled gain, like ROHM BH1600-series. Please see [Table](#page-13-1) 2. LM3537 changes sensor gain automatically based on ambient light intensity changes.

<span id="page-13-1"></span>

# **Table 2. Sensor Gain Control**



The ambient light sensing circuit has 4 configurable Ambient Light Boundaries (ZB0 – ZB3) programmed through the four 8-bit Zone Boundary Registers. These zone boundaries **define 5 ambient brightness zones**.

The ambient light sensor input has a 0 to 1V operational input voltage range. The Typical Application Circuit shows the LM3537 with an ambient light sensor (ROHM, BH1621FVC). If the internal ALS Resistor Select Register is set to 0x14 (1.44 kΩ), this circuit will convert 0 to 1000 LUX light into approximately a 0 to 850 mV linear output voltage (high-gain mode). The voltage at the active ambient light sensor input is compared against the 8-bit values programmed into the Zone Boundary Registers (ALS ZONE BOUNDARY#0 - ALS ZONE BOUNDARY#3 ). When the ambient light sensor output crosses one of the programmed thresholds the internal ALS circuitry will smoothly transition the LED current to the new 7-bit brightness level as programmed into the appropriate Zone Target Register (ALS BRIGHTNESS ZONE#0 to ALS BRIGHTNESS ZONE#4).

Ambient light sensor samples are averaged and then further processed by the discriminator block to provide rejection of noise and transient signals. The averager is configurable with 8 different averaging times to provide varying amounts of noise and transient rejection. The discriminator block algorithm has a maximum latency of two averaging cycles; therefore, the averaging time selection determines the amount of delay that will exist between a steady state change in the ambient light conditions and the associated change of the backlight illumination. For example, the A/D converter samples the ALS inputs at 16 kHz. If the averaging time is set to 800 ms, the averager will send the updated zone information to the discriminator every 800 ms. This zone information contains the average of approximately 12800 samples (800 ms  $\times$  16 kHz). Due to the latency of 2 averaging cycles, when there is a steady state change in the ambient light, the LED current will begin to transition to the appropriate target value after approximately 1600 ms have elapsed.

ALS Zone to LED Brightness Mapping principle without AutoGain is shown in [Figure](#page-14-0) 3 below. Here, the exponential dimming scheme is used.





<span id="page-14-0"></span>ALS Zone transitions with AutoGain is shown in [Figure](#page-15-0) 4. When the light intensity increases, the LM3537 configures the sensor for low-gain mode. Transition from Zone2 to Zone3 triggers the shift to lower gain mode. When the light intensity decreases, the LM3537 configures the sensor to high-gain mode. The trip point to this transition is set by the ALS LOW\_to\_HIGH\_TP register, and it should be set lower than the Zone2 to Zone3 transition, in order to have hysteresis. Zone3 to Zone2 transition trip point must be set separately for lower gain mode, by the ALS ZONE BOUNDARY Z3\_to\_Z2 register. This register value should be set higher than the ALS LOW to HIGH TP. In low-gain mode the sensor will have a lower output current which helps save battery power. High-gain mode will allow better resolution, but will result higher output current. Thus, there is a trade-off between increased resolution and increased power consumption. High-gain mode is the default mode of operation after enabling the autogain.

**FXAS STRUMENTS** 

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There are some limits in Zone transitions when the autogain is enabled, for example a direct transition from the lowest

Zone0 to the highest Zone4 (and vice versa) is not possible, because the device must go through the gain change process first.



## <span id="page-15-0"></span>**Countdown Timer**

The ALS engine includes a pre-defined countdown timer function. This function is targeted to applications where it's favorable to only increase through the zones; i.e., the LM3537 will stick to the highest zone reached, but won't allow transitions to lower Zones until the countdown has completed. At the end of every countdown, the timer sets the countdown timer flag (reg 40H), and after that, any Zone transition to a lower Zone re-loads the timer and starts the next timer period. See [Table](#page-15-1) 3 and [Figure](#page-16-0) 5 for details.

<span id="page-15-1"></span>

### **Table 3. Countdown Timer**



Solid line shows the ALS operation when the timer is disabled. Dashed line shows the operation when the 10s timer is enabled. Dotted line shows the operation when the device sticks to the highest zone.

**Figure 5. Countdown Timer Principle**

## <span id="page-16-0"></span>**PWM Input**

A PWM (Pulse Width Modulation) pin is provided on the LM3537 to allow a display driver utilizing dynamic backlight control (DBC), to adjust the LED brightness based on the content. The PWM input can be turned on or off (Acknowledge or Ignore) and the polarity can be flipped (active high or active low) through the I<sup>2</sup>C interface. The current sinks of the LM3537 require approximately 15 us to reach steady-state target current. This turn-on time sets the minimum usable PWM pulse width for DBC. The external PWM input is effective for group A LEDs only.

## **LED Forward Voltage Monitoring**

The LM3537 has the ability to switch gains (1x or 3/2x) based on the forward voltage of the LED load. This ability to switch gains maximizes efficiency for a given load. Forward voltage monitoring occurs on all diode pins. At higher input voltages, the LM3537 will operate in pass mode, allowing the  $V_{\text{OUT}}$  voltage to track the input voltage. As the input voltage drops, the voltage on the Dx pins will also drop ( $V_{DX} = V_{VOUT} - V_{LEDx}$ ). Once any of the active Dx pins reaches a voltage approximately equal to 150 mV, the charge pump will switch to the gain of 3/2. This switch-over ensures that the current through the LEDs never becomes pinched off due to a lack of headroom across the current sinks. **Once a gain transition occurs, the LM3537 will remain in the gain of 3/2** until an I<sup>2</sup>C write to the part occurs. At that time, the LM3537 will re-evaluate the LED conditions and **select the appropriate gain.**

Only active Dx pins will be monitored.

# **Configurable Gain Transition Delay**

To optimize efficiency, the LM3537 has a user-selectable gain transition delay that allows the part to ignore short duration input voltage drops. By default, the LM3537 will not change gains if the input voltage dip is shorter than 3 to 6 milliseconds. There are four selectable gain transition delay ranges available on the LM3537.

## **Hardware Enable (HWEN)**

The LM3537 has a hardware enable/reset pin (HWEN) that allows the device to be disabled by an external controller without requiring an I<sup>2</sup>C write command. Under normal operation, the HWEN pin should be held high (logic '1') to prevent an unwanted reset. When the HWEN is driven low (logic '0'), all internal control registers reset to the default states, and the part becomes disabled. Please see the *Electrical Characteristics* section of the datasheet for required voltage thresholds.



### **Low Dropout Voltage Regulators**

The four low dropout voltage regulators are designed to operate with small-size ceramic input and output capacitors. They can operate with power rail voltages down to 1.8V. The LDOs 2, 3 and 4 offer a typical dropout voltage of 100 mV at 150 mA output current. The single, higher-current LDO 1 offers a typical dropout voltage of mV at 300mA output current. The LDOs are enabled by the EN\_LDO1, EN\_LDO2, EN\_LDO3 and EN\_LDO4 bits (see [Table](#page-20-0) 5 for details). summarizes the supported output voltages. At startup, the LDOs are off but are preset to 1.8V (for LDO2 and LDO3) and 2.8V (for LDO1 and LDO4).

<span id="page-17-0"></span>

### **Table 4. Regulator Voltage Options**



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The power input voltage applied between  $V_{IN,C}$  and GND should be at least 0.3V above the output voltage of the regulators. The bias input voltage applied between V<sub>IN B</sub> and GND should be equal to V<sub>IN A</sub>, and at least 0.3V above the output voltage of the regulators.



 $V_{\text{IN\_B}}$  supplies internal circuitry.  $V_{\text{IN\_C}}$ , the power input voltage, is regulated to the fixed output voltage.

**Figure 6. LDO Block Diagram**

# **I <sup>2</sup>C-Compatible Interface**

# **STOP AND START CONDITIONS**

The LM3537 is controlled via an I<sup>2</sup>C-compatible interface. START and STOP) conditions classify the beginning and the end of the I<sup>2</sup>C session. A START condition is defined as SDA transitioning from HIGH to LOW while SCL is HIGH. A STOP condition is defined as SDA transitioning from LOW to HIGH while SCL is HIGH. The I<sup>2</sup>C master always generates START and STOP conditions. The <sup>12</sup>C bus is considered busy after a START condition and free after a STOP condition. During data transmission, the I<sup>2</sup>C master can generate repeated START conditions. A START and a repeated START conditions are equivalent function-wise. The data on SDA must be stable during the HIGH period of the clock signal (SCL). In other words, the state of SDA can only be changed when SCL is LOW.



**Figure 7. Start and Stop Sequences**

# **I <sup>2</sup>C-COMPATIBLE CHIP ADDRESS**

The chip address for the LM3537 is 0111000 (38h). After the START condition, the I<sup>2</sup>C master sends the 7-bit chip address followed by a read or write bit (R/W). R/W= 0 indicates a WRITE and R/W = 1 indicates a READ. The second byte following the chip address selects the register address to which the data will be written. The third byte contains the data for the selected register.



**Figure 8. Chip Address**

# **TRANSFERRING DATA**

Every byte on the SDA line must be eight bits long, with the most significant bit (MSB) transferred first. Each byte of data must be followed by an acknowledge bit (ACK). The acknowledge related clock pulse (9th clock pulse) is generated by the master. The master releases SDA (HIGH) during the 9th clock pulse. The LM3537 pulls down SDA during the 9th clock pulse, signifying an acknowledge. An acknowledge is generated after each byte has been received. [Figure](#page-19-0) 9 is an example of a write sequence to the DIODE ENABLE register of the LM3537.

<span id="page-19-0"></span>

**Figure 9. Write Sequence to the LM3537**



# **Internal Registers of LM3537**

The LM3537 is controlled by a set of registers through the two-wire serial interface port. [Table](#page-20-0) 5 below lists device registers and their addresses together with a short description.

<span id="page-20-0"></span>

### **Table 5. Control Register Map**

**Table 5. Control Register Map (continued)**



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(1)  $V_{\text{OUT S}}$  = SBIAS pin output voltage. The voltage level of the GPOs depends on the sbias\_en-bit: '1'; GPOs will behave as push-pull outputs and will reference the high-side to the voltage of SBIAS. '0'; GPOs will act configuration, they can be high-side referenced to any voltage equal to, or less than, the VIN\_A of the LM3537. Output High Level (V<sub>OH</sub>) specification is valid only for push-pull -type outputs.



# **Table 5. Control Register Map (continued)**



### **Current Control Registers**

# **A0 GROUP A BRIGHTNESS**

This is the LED driver current control register for Group A. The register is effective when the ALS isn't used. The resolution is 7 bits, so in linear dimming mode the step size from zero up to full brightness is fixed (25.0mA/127) = 197 µA. Exponential dimming scheme provides a more fine-grained level of control over low level LED currents. Group A exponential dimming curve current can be approximated by the following equation (where N = the decimal value stored in the Group A Brightness register):

# $I_{LED}$  (mA)  $\approx 25 \times 0.85^{[44 - \{(N+1)/2.91\}}$

Current vs. code is shown below.



**Figure 10. LED current (typ.) vs. register code, exponential dimming curve**

## **B0 GROUP B BRIGHTNESS**

Bits [2:0] set the GroupB Brightness Levels, as shown in below:



### **Table 6. Group B Brightness Levels**

(1)



# **APPLICATION INFORMATION**

# **LED CONFIGURATIONS**

The LM3537 has a total of 8 current sinks capable of sinking 180mA of total diode current. These 8 current sinks are configured to operate in one or two independently controlled lighting regions. GroupA has eight dedicated current sinks, while GroupB has 0 by default. However, drivers D5 to D8 can be assigned to either GroupA or GroupB one-by-one through a setting in the configuration register. With this added flexibility, the LM3537 is capable of supporting applications requiring from 4 to 7 LEDs for main display lighting, while still providing additional current sink(s) that can be used for a wide variety of lighting functions.

# **PARALLEL CONNECTED AND UNUSED OUTPUTS**

Connecting the outputs in parallel does not affect internal operation of the LM3537 and has no impact on the Electrical Characteristics and limits previously presented. The available diode output current, maximum diode voltage, and all other specifications provided in the Electrical Characteristics tables apply to this parallel output configuration, just as they do to the standard LED application circuit.

All Dx current sinks utilize LED forward voltage sensing circuitry to optimize the charge-pump gain for maximum efficiency.

If some of the drivers are not going to be used, make sure that the enable bits in the DIODE ENABLE register are set to '0' to ensure optimal efficiency.

# **THERMAL PROTECTION**

Internal thermal protection circuitry disables the LM3537 when the junction temperature exceeds 160°C (typ.). This feature protects the device from being damaged by high die temperatures that might otherwise result from excessive power dissipation. The device will recover and operate normally when the junction temperature falls below 155°C (typ.). It is important that the board layout provide good thermal conduction to keep the junction temperature within the specified operating ratings.

# **CAPACITOR SELECTION**

The LM3537 circuit requires 11 external capacitors for proper operation. Surface-mount multi-layer ceramic capacitors are recommended. These capacitors are small, inexpensive and have very low equivalent series resistance (ESR <20 mΩ typ.). Tantalum capacitors, OS-CON capacitors, and aluminum electrolytic capacitors are not recommended for use with the LM3537 due to their high ESR, as compared to ceramic capacitors.

For most applications, ceramic capacitors with X7R or X5R temperature characteristic are preferred for use with the LM3537. These capacitors have tight capacitance tolerance (as good as  $\pm 10\%$ ) and hold their value over temperature (X7R: ±15% over -55°C to 125°C; X5R: ±15% over -55°C to 85°C).

Capacitors with Y5V or Z5U temperature characteristic are generally not recommended for use with the LM3537. Capacitors with these temperature characteristics typically have wide capacitance tolerance (+80%, -20%) and vary significantly over temperature (Y5V: +22%, -82% over -30°C to +85°C range; Z5U: +22%, -56% over +10°C to +85°C range). Under some conditions, a nominal 1µF Y5V or Z5U capacitor could have a capacitance of only 0.1µF. Such detrimental deviation is likely to cause Y5V and Z5U capacitors to fail to meet the minimum capacitance requirements of the LM3537.

[Table](#page-26-0) 7 below lists recommended external capacitors from some leading ceramic capacitor manufacturers. It is strongly recommended that the LM3537 circuit be thoroughly evaluated early in the design-in process with the mass-production capacitors of choice. This will help ensure that any variability in capacitance does not negatively impact circuit performance.



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# **Table 7. Suggested Capacitors**

<span id="page-26-0"></span>

<span id="page-26-1"></span>(1) The recommended voltage rating for these capacitors is 10V to account for DC bias capacitance losses.

# **REVISION HISTORY**

# **Changes from Revision A (May 2013) to Revision B Page** • Changed layout of National Data Sheet to TI format .. [27](#page-26-1)





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# **PACKAGING INFORMATION**



**(1)** The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures. "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

**(3)** MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**(4)** There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

**(5)** Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

**(6)** Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

# **PACKAGE MATERIALS INFORMATION**

**TEXAS NSTRUMENTS** 

\*All dimensions are nominal

# **TAPE AND REEL INFORMATION**





# **QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**







# **PACKAGE MATERIALS INFORMATION**

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\*All dimensions are nominal





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